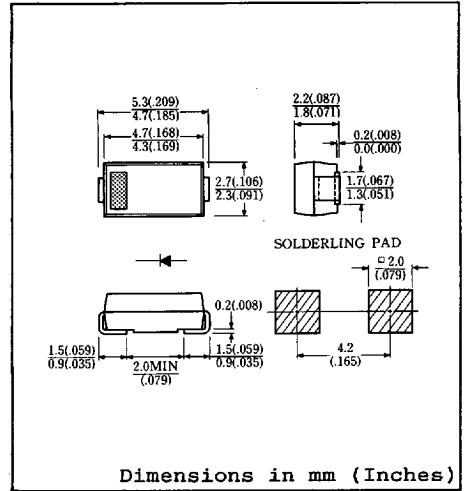


FEATURES

- Miniature Size, Surface Mount Device
- Ultra - Fast Recovery
- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- High Surge Capability
- 100 Volts through 400 Volts Types Available
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly



Approx. Net Weight: 0.06 Grams

MAXIMUM RATINGS

Voltage Rating	TYPE	♦ EC11FS1	EC11FS2	Unit		
	Symbol					
Repetitive Peak Reverse Voltage	V_{RRM}	100	200	V		
Non-Repetitive Peak Reverse Voltage	V_{RSM}	110	220	V		
Electrical Rating	Symbol	Condition		Rating	Unit	
Average Rectified Output Current	I_o	Ceramic substrate mounted *	180° rectangular wave conduction	$T_a = 25^\circ C$	1.1	A
			180° sinusoidal wave conduction	$T_a = 34^\circ C$	1.0	
		Glass-Epoxy substrate *	$T_a = 25^\circ C$	0.8		
RMS Forward Current	$I_{F(RMS)}$			1.57	A	
Peak One-cycle Forward Surge Current	I_{FSM}	50Hz half sine wave, non-repetitive		20	A	
Operating Junction Temperature Range	T_{jw}			-40 to 150	°C	
Storage Temperature Range	T_{stg}			-40 to 150	°C	

ELECTRICAL & THERMAL CHARACTERISTICS

Characteristics	Symbol	Test Condition	Max.	Unit
Peak Forward Voltage	V_{FM}	$I_{FM} = 1.0A$ $T_j = 25^\circ C$	0.98	V
Peak Reverse Current	I_{RM}	$V_{RM} = V_{RRM}$ $T_j = 25^\circ C$	10	μA
Reverse Recovery Time	t_{rr}	$I_{FM} = 1A$ $-di/dt = 50A/\mu s$ $T_a = 25^\circ C$	30	ns
Thermal Resistance, junction to ambient	$R_{th(j-a)}$	Ceramic substrate mounted *	108	°C/W
		Glass-Epoxy substrate mounted *	157	

* Substrate Soldering Land = 2 x 2 mm
 ♦ For spare parts only

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FIG.1-FORWARD CURRENT VS. FORWARD VOLTAGE

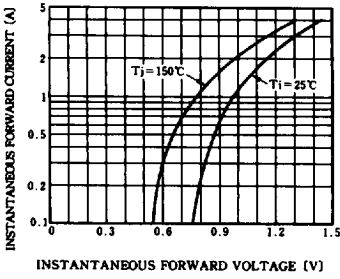


FIG.2-AVERAGE FORWARD POWER DISSIPATION

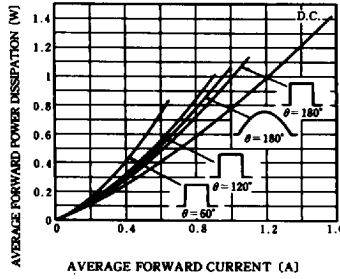


FIG.3-AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

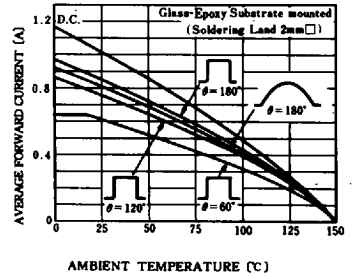


FIG.4-AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

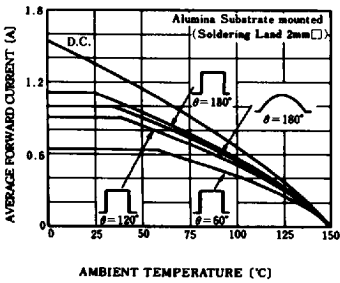
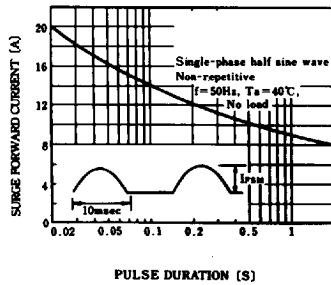


FIG.5-SURGE CURRENT RATINGS



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